Power Present TDR test results for all signal layers.

4. 1 oz copper for all power layers and for Signal_1,2 (Top and Bottom)

2. Minimum trace width: 0.005" and clearance: 0.005"

Perform TDR test for all signal layers. Present TDR test results for all signal layers.

Apply Solder Mask over bare copper.

Board Characteristics:

8. Silkscreen on both Sides.

10. FHM tolerances: 4/- 0.003

11. Interlayer spacing as specified

12. 25 x 20 0.01 in 4 - 5.8mm